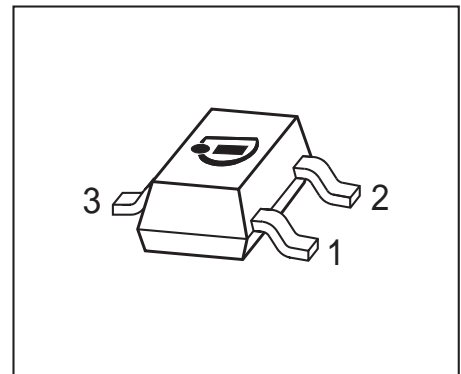


NPN Silicon RF Transistor*

- For broadband amplifiers up to 2 GHz and fast non-saturated switches at collector currents from 0.5 mA to 20 mA
- Complementary type: BFT91 (PNP)
- Pb-free (RoHS compliant) package ¹⁾
- Qualified according AEC Q101



* Short term description



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Marking	Pin Configuration			Package
BFR92P	GFs	1=B	2=E	3=C	SOT23

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	15	V
Collector-emitter voltage	V_{CES}	20	
Collector-base voltage	V_{CBO}	20	
Emitter-base voltage	V_{EBO}	2.5	
Collector current	I_C	45	mA
Base current	I_B	4	
Total power dissipation- $T_S \leq 48 \text{ }^\circ\text{C}$	P_{tot}	280	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Ambient temperature	T_A	-65 ... 150	
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ²⁾	R_{thJS}	≤ 365	K/W

¹Pb-containing package may be available upon special request

²For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 1\text{ mA}, I_B = 0$	$V_{(BR)CEO}$	15	-	-	V
Collector-emitter cutoff current $V_{CE} = 20\text{ V}, V_{BE} = 0$	I_{CES}	-	-	10	μA
Collector-base cutoff current $V_{CB} = 10\text{ V}, I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 2.5\text{ V}, I_C = 0$	I_{EBO}	-	-	100	μA
DC current gain- $I_C = 15\text{ mA}, V_{CE} = 8\text{ V}, \text{ pulse measured}$	h_{FE}	70	100	140	-

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

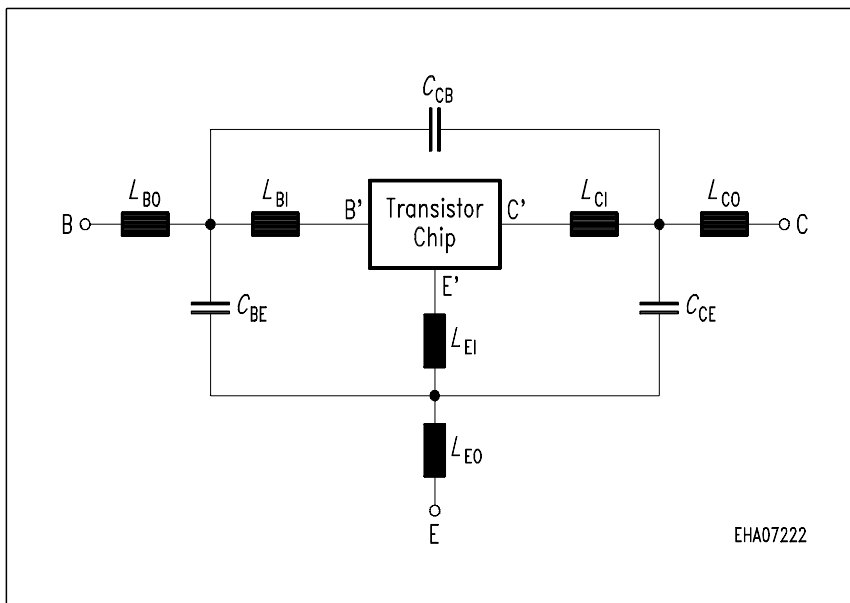
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency $I_C = 15 \text{ mA}$, $V_{CE} = 8 \text{ V}$, $f = 500 \text{ MHz}$	f_T	3.5	5	-	GHz
Collector-base capacitance $V_{CB} = 10 \text{ V}$, $f = 1 \text{ MHz}$, $V_{BE} = 0$, emitter grounded	C_{cb}	-	0.39	0.55	pF
Collector emitter capacitance $V_{CE} = 10 \text{ V}$, $f = 1 \text{ MHz}$, $V_{BE} = 0$, base grounded	C_{ce}	-	0.23	-	
Emitter-base capacitance $V_{EB} = 0.5 \text{ V}$, $f = 1 \text{ MHz}$, $V_{CB} = 0$, collector grounded	C_{eb}	-	0.64	-	
Noise figure $I_C = 2 \text{ mA}$, $V_{CE} = 6 \text{ V}$, $Z_S = Z_{Sopt}$, $f = 900 \text{ MHz}$ $I_C = 2 \text{ mA}$, $V_{CE} = 6 \text{ V}$, $Z_S = Z_{Sopt}$, $f = 1.8 \text{ GHz}$	F	-	1.4	-	dB
		-	2	-	
Power gain, maximum available ¹⁾ $I_C = 15 \text{ mA}$, $V_{CE} = 8 \text{ V}$, $Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$, $f = 900 \text{ MHz}$ $I_C = 15 \text{ mA}$, $V_{CE} = 8 \text{ V}$, $Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$, $f = 1.8 \text{ GHz}$	G_{ma}	-	16	-	
		-	10.5	-	
Transducer gain $I_C = 15 \text{ mA}$, $V_{CE} = 8 \text{ V}$, $Z_S = Z_L = 50 \Omega$, $f = 900 \text{ MHz}$ $I_C = 15 \text{ mA}$, $V_{CE} = 8 \text{ V}$, $Z_S = Z_L = 50 \Omega$, $f = 1.8 \text{ MHz}$	$ S_{21e} ^2$	-	13	-	dB
		-	7.5	-	

$$^1G_{ma} = |S_{21e} / S_{12e}| (k - (k^2 - 1)^{1/2})$$

SPICE Parameter (Gummel-Poon Model, Berkley-SPICE 2G.6 Syntax):
Transistor Chip Data:

IS =	0.1213	fA	BF =	94.733	-	NF =	1.0947	-
VAF =	30	V	IKF =	0.46227	A	ISE =	129.55	fA
NE =	1.9052	-	BR =	10.729	-	NR =	0.8983	-
VAR =	14.599	V	IKR =	0.01	A	ISC =	0.75557	fA
NC =	1.371	-	RB =	14.998	Ω	IRB =	0.01652	mA
RBM =	7.8145	Ω	RE =	0.29088	-	RC =	0.13793	Ω
CJE =	10.416	fF	VJE =	0.70618	V	MJE =	0.34686	-
TF =	26.796	ps	XTF =	0.3817	-	VTF =	0.32861	V
ITF =	4.4601	mA	PTF =	0	deg	CJC =	946.47	fF
VJC =	0.84079	V	MJC =	0.4085	-	XCJC =	0.13464	-
TR =	1.2744	ns	CJS =	0	fF	VJS =	0.75	V
MJS =	0	-	XTB =	0	-	EG =	1.11	eV
XTI =	3	-	FC =	0.99545	-	TNOM	300	K

All parameters are ready to use, no scaling is necessary. Extracted on behalf of Infineon Technologies AG by: Institut für Mobil- und Satellitentechnik (IMST)

Package Equivalent Circuit:


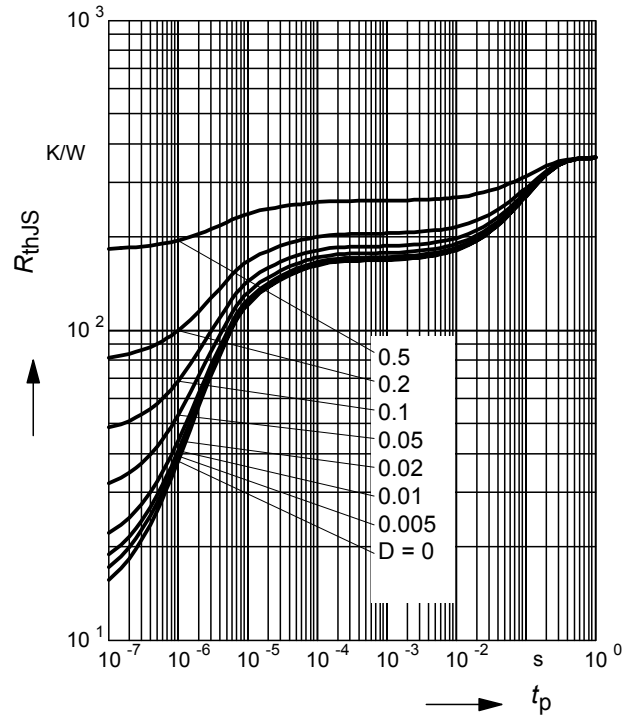
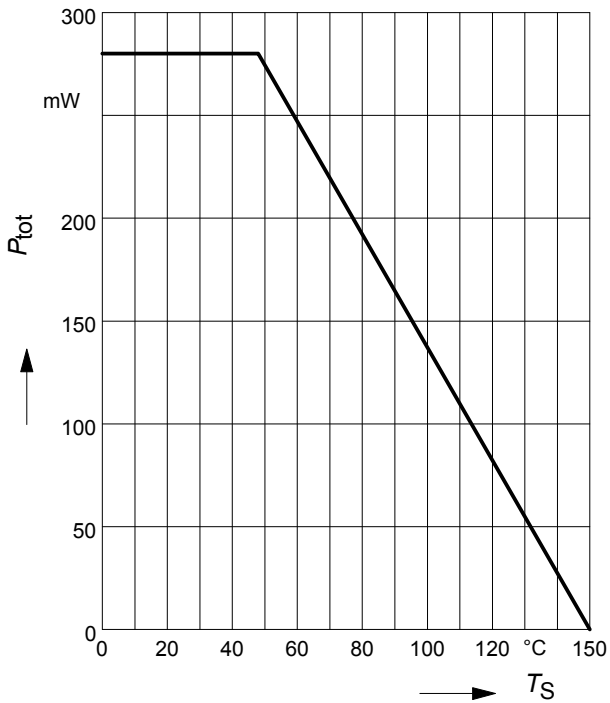
$L_{BI} =$	0.85	nH
$L_{BO} =$	0.51	nH
$L_{EI} =$	0.69	nH
$L_{EO} =$	0.61	nH
$L_{CI} =$	0	nH
$L_{CO} =$	0.49	nH
$C_{BE} =$	73	fF
$C_{CB} =$	84	fF
$C_{CE} =$	165	fF

Valid up to 6GHz

For examples and ready to use parameters please contact your local Infineon Technologies distributor or sales office to obtain a Infineon Technologies CD-ROM or see Internet: <http://www.infineon.com>

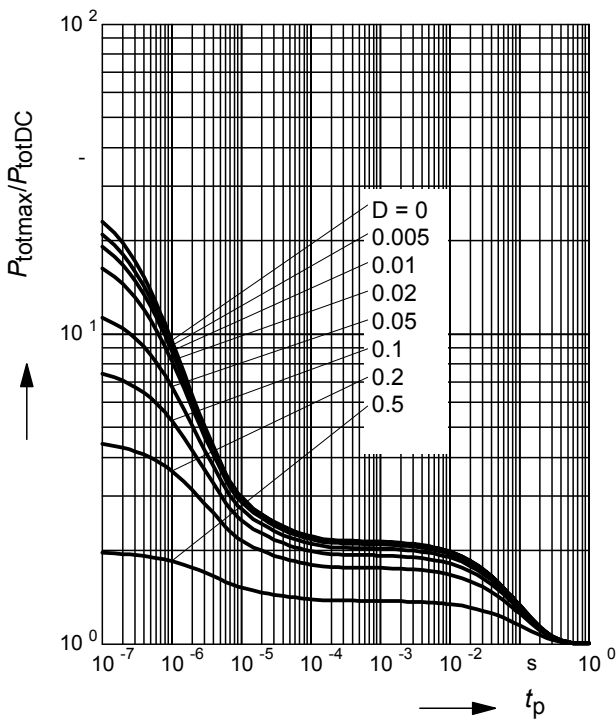
Total power dissipation $P_{tot} = f(T_S)$

Permissible Pulse Load $R_{thJS} = f(t_p)$

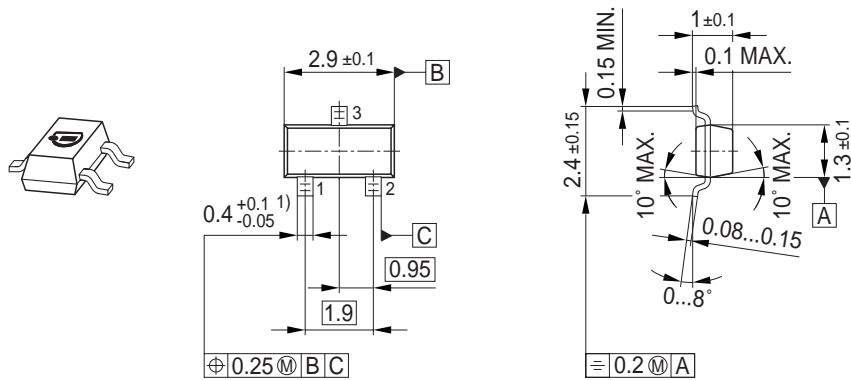


Permissible Pulse Load

$P_{totmax}/P_{totDC} = f(t_p)$

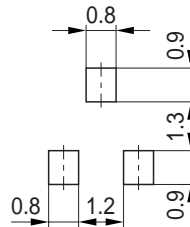


Package Outline

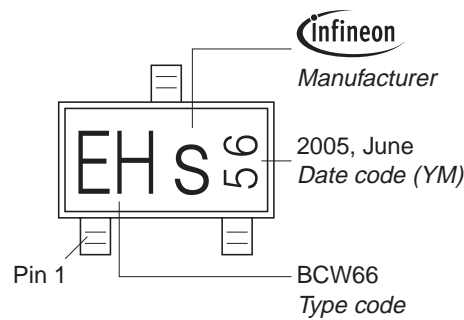


1) Lead width can be 0.6 max. in dambar area

Foot Print

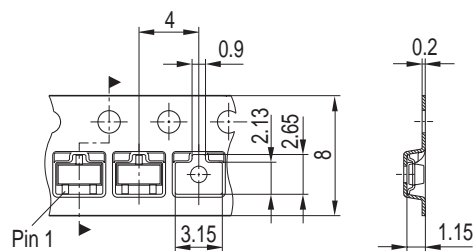


Marking Layout (Example)



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



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